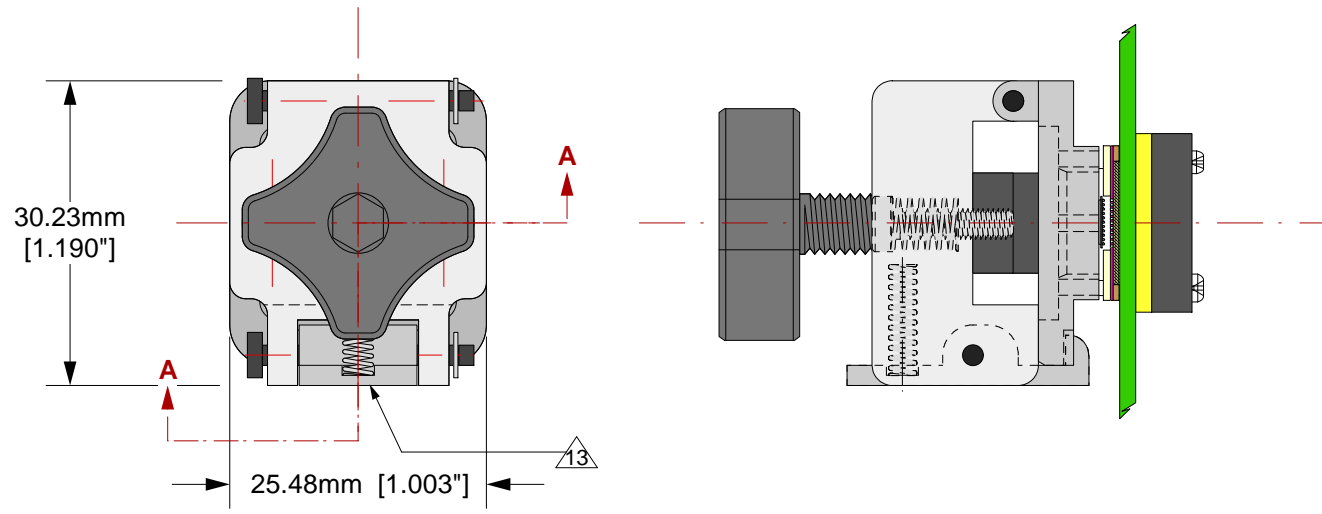
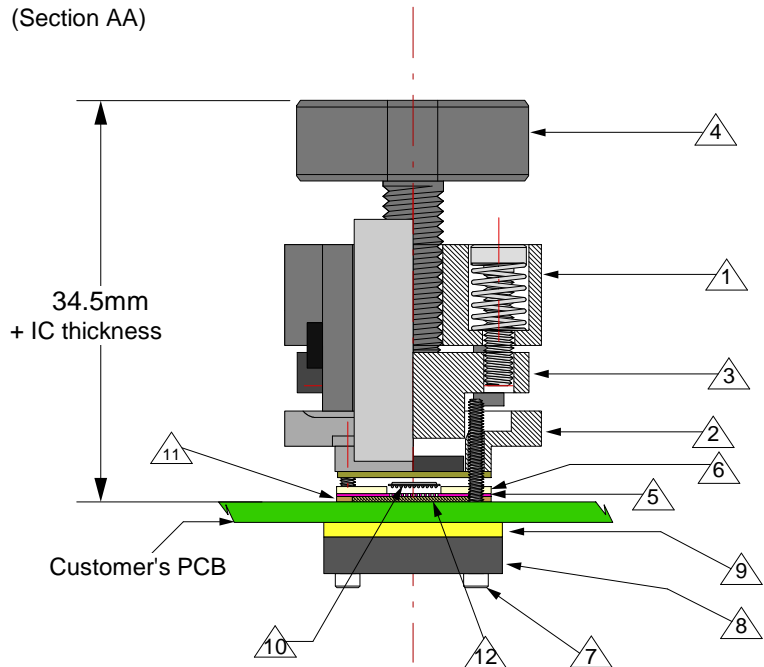


Top View



Side View
(Section AA)




Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

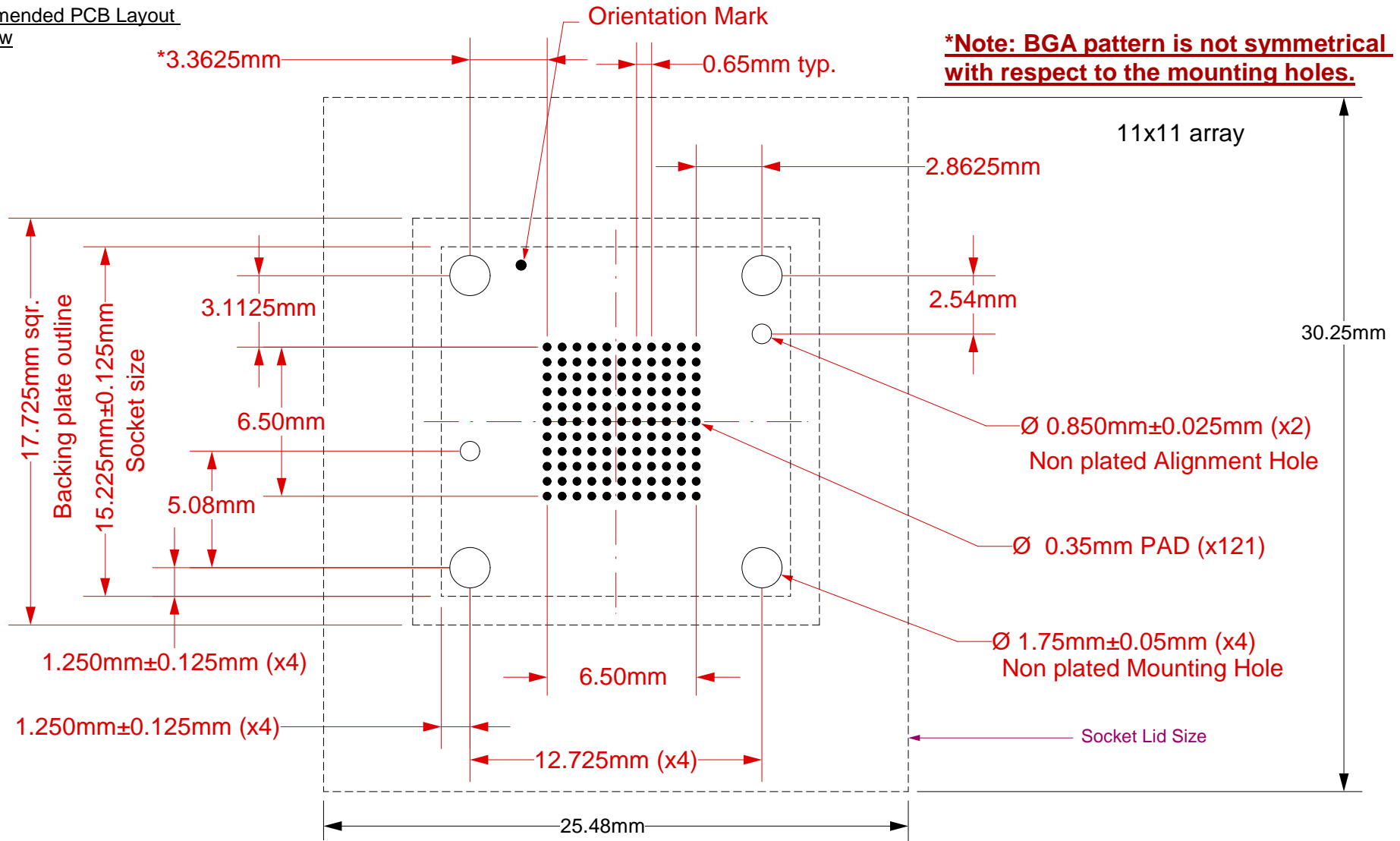
Materials:

- 1 Clam Shell Lid: Black anodized Aluminum. Height = 16.5 mm.
- 2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 8.5 mm.
- 4 Compression Screw: Clear anodized Aluminum. Height = 25 mm, Fluted Knob
- 5 Ball Guide: Kapton polyimide.
- 6 IC Guide: Torton
- 7 Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 5/8" long.
- 8 Backing Plate: Black anodized Aluminum. Thickness= 4mm
- 9 Insulation Plate: FR4/G10
- 10 Customer's BGA IC
- 11 Elastomer Guide: Non-clad FR4. Thickness = 0.475mm.
- 12 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- 13 Latch: Black anodised Aluminum.

	CG-BGA-5004 Drawing	Status: Released	Scale: 1.33:1	Rev: B
	© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: S. Natarajan		Date: 04/02/2010
		File: CG-BGA-5004 Dwg.mcd	Modified: 09/17/14	

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View




Target PCB Recommendations

Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

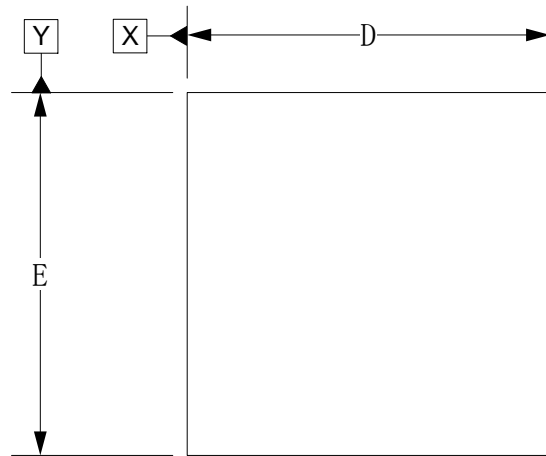
All dimensions are in mm unless stated otherwise

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

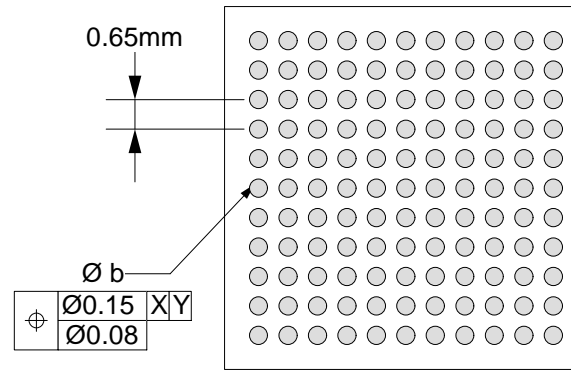
	CG-BGA-5004 Drawing	Status: Released	Scale: 4:1	Rev: B
	© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: S.Natarajan		Date: 04/02/2010
		File: CG-BGA-5004 Dwg.mcd	Modified: 09/17/14	

Recommended PCB Layout Tolerances:
±0.025mm [±0.001"] unless stated otherwise.

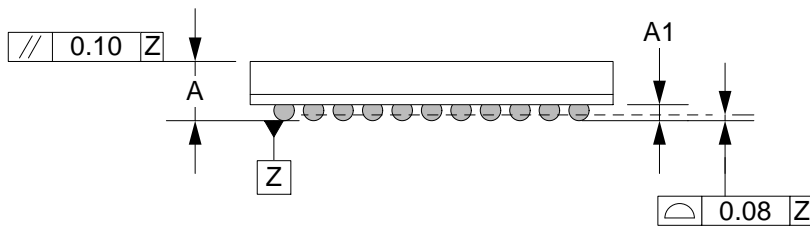
Compatible BGA Spec.



Top View



Bottom View




Side View

1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

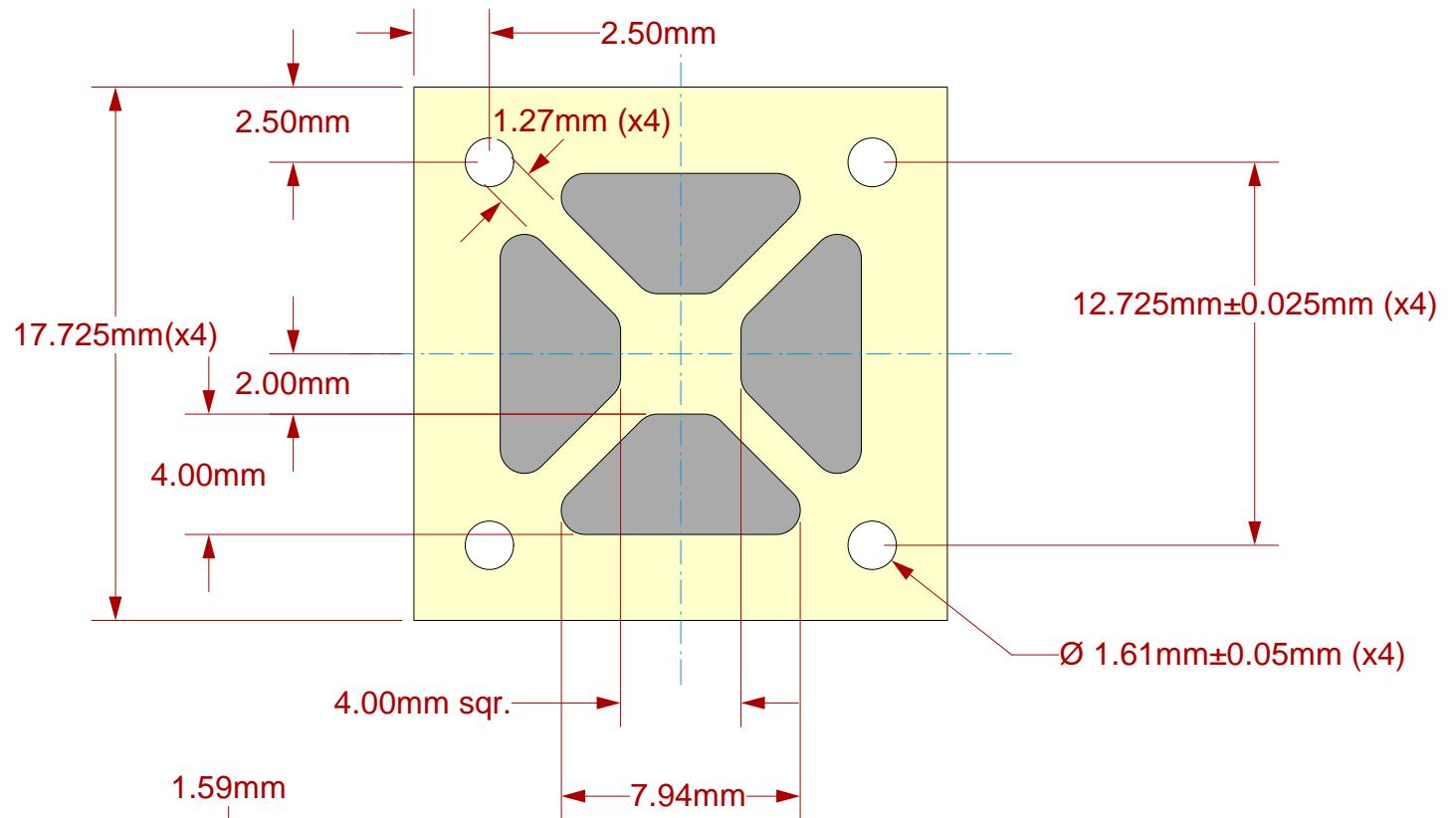
DIM	MIN	MAX
A		1.2
A1	0.27	0.37
b	0.35	0.45
D	8.0 BSC	
E	8.0 BSC	
e	0.65 BSC	

Array: 11x11

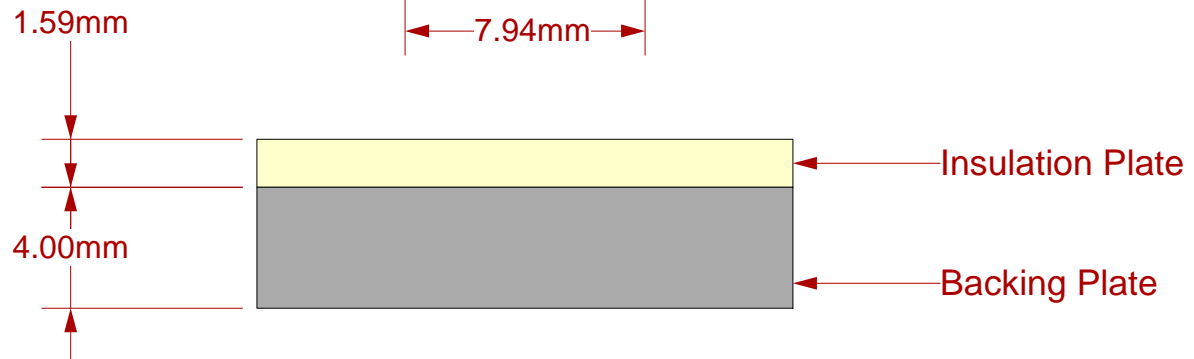
	CG-BGA-5004 Drawing © 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Status: Released	Scale: 8:1	Rev: B
		Drawing: S.Natarajan		Date: 04/02/2010
		File: CG-BGA-5004 Dwg.mcd		Modified: 09/17/14

Top View


Top View



Side View



Description: Backing Plate with Insulation Plate

	CG-BGA-5004 Drawing	Status: Released	Scale: 4:1	Rev: B
	© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: S.Natarajan		Date: 04/02/2010
		File: CG-BGA-5004 Dwg.mcd	Modified: 09/17/14	

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)